Gap Pad VO® is a cost-effective, thermally conductive interface material. The material is a filled, thermally conductive polymer supplied on a rubber-coated fiberglass carrier allowing for easy material handling. The conformable nature of Gap Pad VO® allows the pad to fill in air gaps between PC boards and heat sinks or a metal chassis.

Note: Resultant thickness is defined as the final gap thickness of the application.

**Typical Applications Include:**
- Telecommunications
- Computer and peripherals
- Power conversion
- Between heat-generating semiconductors and a heat sink
- Area where heat needs to be transferred to a frame, chassis, or other type of heat spreader
- Between heat-generating magnetic components and a heat sink

**Configurations Available:**
- Sheet form and die-cut parts

**Building a Part Number**

<table>
<thead>
<tr>
<th>Section A</th>
<th>Section B</th>
<th>Section C</th>
<th>Section D</th>
<th>Section E</th>
</tr>
</thead>
<tbody>
<tr>
<td>GPVO</td>
<td>0.040</td>
<td>AC</td>
<td>0816</td>
<td>NA</td>
</tr>
</tbody>
</table>

NA = Selected standard option. If not selecting a standard option, insert company name, drawing number, and revision level.

0816 = Standard sheet size 8” x 16” or custom configuration

AC = Adhesive on Sil-Pad® side, natural tack on one side

00 = No pressure sensitive adhesive, natural tack on one side

Standard thicknesses available: 0.020”, 0.040”, 0.060”, 0.080”, 0.100”, 0.125”, 0.160”, 0.200”, 0.250”

**Standard Options**
- GPVO = Gap Pad VO® Material

**Gap Pad VO®** U.S. Patent 5,679,457 and others